

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

<b>Applicant(s):</b> Chen, et al	<b>Conf. No.:</b> 1057
<b>Serial No.:</b> 10/604,058	<b>Art. Unit:</b> 1763
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<b>Title:</b> <b>PLASMA PROCESSING MATERIAL RECLAMATION AND REUSE</b>	<b>Docket. No.:</b> FIS920030132US1 (IBMF-0018)

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**AMENDMENT**

Sir:

**I. INTRODUCTORY COMMENTS**

This paper is in response to the Office Action of 4 January 2007. Please amend the above-referenced patent application as follows:

**The Amendments to the Claims** are reflected in the listing of the claims that begins on page 2 of this paper.

**Remarks** begin on page 8 of this paper.

**The Conclusion** appears on page 10 of this paper.